



**PILOT NEXT> LINE**

## PILOT VB NEXT>

The **PILOT VB NEXT>** represents the latest frontier in flying probe test technology; it is the complete solution for those who want maximum performance: the highest test speed, low to medium volume, test coverage and flexibility, for prototyping, manufacturing, or repairing any type of board. Its vertical architecture is the optimum solution for probing both sides of the UUT simultaneously. This increases test throughput and flexibility while guaranteeing fast, precise, reliable and repeatable probing and full availability of all the mobile resources for testing the UUT. This solution represents an important technological innovation in double-sided flying probe test, overcoming the intrinsic limitations of horizontal systems. The **PILOT VB NEXT>** is equipped with 8 electrical flying test probes (4 on each side), 2 Openfix flying probes (1 on each side), 2 power flying probes (1 on each side) and 2 CCD cameras (1 on each side), 2 Thermal Scan sensors, 2 Laser sensors, 2 LED Sensors, for a total of **20 mobile resources available to test the UUT**. The mobile power probes are another important innovation which enables power up of the UUT without requiring any additional fixed cables, allowing easy implementation of functional test. Available in the **Manual** and **Automatic** version.

### THE TEST TOOLS AND TECHNIQUES INCLUDE:

- FNODE signature analysis on the nets of the UUT
- Standard analog and digital in-circuit test
- Vectorless tests (AUTIC and OPENFIX), to test ICs for opens and shorts
- PWMON digital net analysis
- Continuity test to detect open tracks on the PCB
- Visual tests for component presence/absence and rotation
- Optional functional test and boundary scan test capabilities
- On Board Programming tools for digital devices
- Optional Thermal Scan Resources
- ALI: Automatic Laser Inspection for presence/absence and warpage compensation
- LED Sensor for light intensity and colour recognition



All of these measurement capabilities and techniques can be combined in a single test program. Important innovations, such as the net-oriented, FNODE and PWMON measurement techniques, provide high fault coverage with significant savings in terms of programming and test time. In addition, with its full complement of test resources, the **PILOT VB NEXT> SERIES** can utilize the test programs developed on any other Seica flying probe system, since it has the capability to operate in all prober configurations (2 or 4 probes on a single side or on both sides).

### VIVA>NEXT> Software and MES integration Option

Like any other Seica solution, the **PILOT VB NEXT>** test system, uses the **VIVA>NEXT>** platform, which provides 2 authentication methods managed through the Seica proprietary graphic editor **MY VIEW**: the standard Windows authentication and the new 'VIVA User Authentication' through which the customer can select the user with different privileges. Since the customer manages the production and material flow through the **MES software**, the Seica **PILOT VB NEXT>** can be connected to the customer MES (Manufacturing Execution System). Through its proprietary Adapter, Seica can integrate all customer MES platforms.



### Industrial Monitoring & Industry 4.0

The Information and technology needed to collect and analyze data, is key to the successful digitalization of the manufacturing process, which is at the heart of the **Industry 4.0** concept. Special attention needs to be given to energy savings and predictive monitoring of events. **Canavisia**, a **Seica Company**, introduces *ShoeBox*, a noninvasive control unit that allows to control energy consumption and to reduce costs and wastes through Monitoring of consumption, Data analysis, Intervention planning.

## TECHNICAL TABLE



**VIVA NEXT** is available in a 32 and 64 bit version with a new graphical interface and a guided environment for an easy and quick test program creation. It is fully integrated with NI-VISA drivers and with third-party test management software.



### SEICA WORLDWIDE



**SEICA SpA**  
via Kennedy 24  
10019 Strambino - TO  
ITALY  
Tel: +39 0125 6368.11  
Fax: +39 0125 6368.99  
Email: sales@seica.com

### PROXIMA S.r.l.

Email: info@proxima-ate.com



**SEICA Inc.**  
Email: DavidSiglio@seicausa.com



**SEICA FRANCE SARL**  
Email: dupoux@seica.fr



**SEICA DEUTSCHLAND GmbH**  
Email: marc.schmuck@seica-de.com



**SEICA ELECTRONICS (Suzhou) Co.Ltd.**  
Email: seicachina@seica.com

Seica reserves the right to change the technical specifications without notice

## PROBES AND CAMERAS

Probes Position - Test Side	Front/Rear
Maximum Number of Resources	20
Number of Electrical Probes	8 (4 front, 4 rear)
Number of Openfix Probes	2 (1 front, 1 rear)
Number of Power Probes	2 (1 front, 1 rear)
Number of Fixed Probes / Upgrade Up To	0/192
Maximum Digital Embedded Channels	4
Number of CCD Colour Cameras	2 (1 front, 1 rear)
Automatic Marker Recognition	Yes
Automatic UUT Planarity Compensation	Yes
Thermal Scan Module (option)	2 (1 front, 1 rear)

## BOARD CLAMPING SYSTEM, UUT SIZES AND WORK AREA (\*)

Board Clamping System	<i>Manual</i> (Dual Action)	
Active Test Area	(610 x 538) mm (24" x 21.18")	<i>Manual</i>
	(610 x 518) mm (24" x 20.39")	<i>Automatic</i>
Board Size	(610 x 540) mm (24" x 21.25")	<i>Manual</i>
	(610 x 520) mm (24" x 20.47")	<i>Automatic</i>
Minimum Board Size (*)	(20 x 20) mm (0.78" x 0.78")	
Maximum Board Thickness	5 mm (0.19")	<i>Manual</i> / 3mm (0.18") <i>Automatic</i>
Minimum Board Thickness	0.3 mm (0.00118")	<i>Manual</i> / 1mm (0.00393") <i>Automatic</i>
Maximum Component Height	37 mm (1.456")	<i>Automatic</i>
Board Loading	Vertical	
UUT Fly Height Clearance	Front (mm)	Back (mm)
4 x 4	40	40
4 x 2	40	90
4 x 0	40	300
2 x 2	90	90
2 x 4	90	40
0 x 4	300	40
UUT Edge Clearance	2 mm <i>Manual</i> / 6 mm <i>Automatic</i>	

## PITCH

Minimum Pad Pitch	150 µm (6 mil)
Minimum Pad Size	50 µm (2 mil)

## PROBE FEATURES

Z-axis Travel	-3.0 mm to 40 mm programmable
Contact Force	5 g – 100 g programmable

## TESTS AND MEASUREMENTS (INSTRUMENTS DSP)

Voltage Generator 1 DC/AC (DRA)	±1 mV to ±10 V (±0.1%)
Voltage Generator 2 DC/AC (DRB)	±1 mV to ±10 V (±0.1%)
Voltage Generator 3 DC/AC (DRC)	±25 mV to ±100 V (±0.2%)
Current Generator DC/AC	±1 nA to ±0.5 A (±0.1%)
Waveform Generator 1 Sin, Tri, Arbitrary (DRA)	1 Hz to 3 MHz (±1 mHz) - ±10 V max
Waveform Generator 2 Sin, Tri, Arbitrary (DRC)	1 Hz to 10 KHz (±10 mHz) - ±100 Vmax
Voltage Measurements DC/AC	±200 µV to ±100 V
Current Measurements DC/AC	±3 nA to ±0.5 A
Frequency Measurement	0.1 Hz to 50 MHz
Digital Embedded Channel	±12 V - 500 mA - 10 MHz
Resistance Measurement	1 mΩ to 100 MΩ
Capacitance Measurement	1 pF to 1 F
Inductor Measurement	1 µH to 1 H
Zener Measurement	up to 100 V (200V option)
Automatic Visual Inspection	Yes

## GENERAL REQUIREMENTS

Temperature Range	25°C ± 10°C	
Humidity	30 - 80 %	
	<b>System</b>	<b>Loader</b>
Power	220 V/50 Hz 12 A, 110 V/60 Hz 24 A	220 V/50 Hz 2 A
Power Consumption	3.5 kW max	1.0 kW max
Air Flow	0.35 CFM - 10l/min.	0.3 CFM - 6l/min.
Weight	1350 kg (2976 lbs)	200 Kg (441 lbs)
Length	175 cm (68.9")	206 cm (81.10")
Width	123 cm (48.4")	155 cm (61.02")
Height	174 cm (68.50")	174 cm (68.50") (214 cm with light-tower)

## SOFTWARE FEATURES

PC/Operating System	Windows 10
Software Architecture	VIP Platform - VIVA NEXT
Automatic Test Generation	Yes
Autodebug	Yes
Data Input Format	CAD Data/Manual
Parallel Test Capabilities	Yes

\*Universal carrier for unique board configurations.